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Form PTO-1595 (Rev. 03 OMB No. 0651-0027 (exp	. 03/31/2015)	U.S. DEPARTMENT OF COMMERC United States Patent and Trademark Office
	RECORDATION FO	RM COVER SHEET
	PATENT	SONLY
To the Director of th	e U.S. Patent and Trademark Office: Pleas	e record the attached documents or the new address(es) below.
1. Name of conve	ying party(les):	2. Name and address of receiving party(les)
Tadashi Morita		Name: Sony Corporation
		Internal Address:
Additional name(s) of cor	nveying party(les) stached? Yes X No	Street Address:
3. Nature of convey	rance/Execution Date(a):	1-7-1 Konan, Minato-ku
Execution Date(s):	November 11, 2013	Tokyo
X Assignment	Merger Change of Name	J 108-0075 JAPAN
	ent Joint Research Agreement	City
	rest Assignment	City:State:
Executive Order	9424, Confirmatory License	
Other	· · · · · · · · · · · · · · · · · · ·	Country: Zip: Additional name(s) & address(es) Yes X No
		attached?
A. Patent Application	• • •	B. Petent No.(s)
6. Name and address concerning docume	to whom correspondence ent should be mailed:	6. Total number of applications and patents involved:
	Dennis M. Smid, Esq. NER, DAVID, LITTENBERG, UMHOLZ & MENTLIK, LLP	7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00
	Dkt.: SONYJP 3,3-2833	
Street Address: 600 South Avenue West		X Authorized to be charged to deposit account
		Enclosed
		None required (government interest not affecting title)
		The reduined (Books untell filterest flot anecticity file)
City:	Westfield	8. Payment information
State: N		
Phone Number:	908-654-5000	42.42
Fax Number:	908-654-7866 mcormier@ldlkm.com	Deposit Account Number 12-1095 Authorized User Name Dennis M. Smid, Esq.
). Signature:	7. TOO THICK WORK TOOM	Definis IV. Smid, Esq.
. Signature.	-11/1	
	Signature	
E	Dennis M. Smid, Esq 34,930	Total cumber of money leak-alles and a
	Name of Person Signing	sheet, attachments, and documents:

3410997

PATENT REEL: 032093 FRAME: 0513

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Attorney Docket No. SONYJP 3.3-2833 SONY Ref. No.:SP334010US00

ASSIGNMENT

WHEREAS, I, as below named inventors, residing at the addresses stated next to our names, am a sole inventor (if only one name is listed below) or a joint inventor (if plural names are listed below) of certain new and useful improvements in INFORMATION PROCESSING APPARATUS, INFORMATION PROCESSING METHOD AND COMPUTER PROGRAM

for which application for Letters Parent of the United States of America was executed by me on the date indicated next to my name and address;

AND WHEREAS, SONY CORPORATION, a Japanese corporation, with offices at 1-7-1 Konan. Minato-ku, Tokyo, Japan (hereinafter referred to as ASSIGNEE) is destrous of acquiring all interest in, to and under said invention, said application disclosing the invention and in, to and under any Letters Patent or similar legal protection which may be granted therefor in the United States and in any and all foreign countries;

NOW THEREPORE, in consideration of the sum of One Dollar (\$1.00), and other good and valuable consideration, the receipt and sufficiency of which are hereby acknowledged. It as a sole or joint inventor as indicated below, by these presents do hereby assign, sell and transfer unto the said ASSIGNEE, its successors, assigns, and legal representatives, the entire right, title and interest in the said invention, said application, including any divisions and continuations thereof, and in and to any and all Letters Patent of the United States, and countries foreign thereto, the Protection of Industrial Property, Inter-American Convention Relating to Patents, Designs and Industrial Models, and any other international agreements to which the United States of America adheres, and to any other benefits accruting or to accrue to me with respect to the filing of applications for patents or securing of patents in the United States and countries foreign thereto, and I hereby authorize and request the Commissioner of Patents to issue the said United States Letters Patent to said ASSIGNEE, as the assignee of the whole right, title and interest thereto:

And I further agree to execute all necessary or desirable and lawful future documents, including assignments in favor of ASSIGNEE or its designee, as ASSIGNEE or its successors, assigns and legal representatives may from time-to-time present to me and without further remuneration, in order to perfect title in said invention, modifications, and improvements in said invention, applications and Letters Patent of the United States and countries foreign thereto;

And I further agree to properly execute and deliver and without further remuneration, such necessary or desirable and lawful papers for application for foreign patents, for filing subdivisions of said application for patent, and or, for obtaining any reissue or reissues of any Letters patent which may be granted for my aforesaid invention, as the ASSIGNEE thereof shall hereafter require and prepare at its own expense:

And I further agree that ASSIGNEE will, upon its request, be provided promptly with all pertinent facts and documents relating to said application, said invention and said Letters Patent and legal equivalents in foreign countries as may be known and accessible to me and will testify as to the same in any interference or litigation related thereto;

And I hereby covenant that no assignment, sale, agreement or encumbrance has been or will be made or entered into which would conflict with this assignment and sale.

TADASHI MORITA	
Name of first or sole inventor TOKYO, JAPAN	Execution date of U.S. Patent Application
Residence of First or sole inventor Signature of first or sole inventor	November 11. 2013
Name of second inventor	Date of this assignment
Residence of second inventor	Execution date of U.S. Patent Application
Signature of second inventor	Date of this assignment
Name of third inventor	Execution date of U.S. Patent Application
Residence of third inventor	
Signature of third inventor	Date of this assignment

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PATENT REEL: 032093 FRAME: 0514

RECORDED: 12/31/2013